

N-Channel SiC Power MOSFET

Features

- High Blocking Voltage with Low On-Resistance
- High Speed Switching with Low Capacitance
- Easy to Parallel and Simple to Drive

Benefits

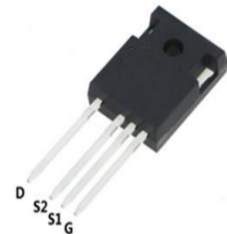
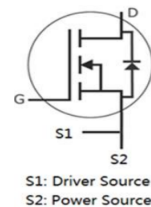
- Higher System Efficiency
- Reduced Cooling Requirements
- Increased Power Density
- Increased System Switching Frequency

Applications

- Solar and UPS inverters
- EV motor drive
- High voltage DC/DC converters
- Switched mode power supplies
- Load switch
- Halogen-free

V_{DS}	=	1200	V
$R_{DS(on)}$	=	16	mΩ
$I_D@25^{\circ}C$	=	120	A

Package



Part Number	Package	Marking
RSM120N120T7L	TO-247-4	120N120

Maximum Ratings ($T_c=25^{\circ}C$ unless otherwise specified)

Symbol	Parameter	Value	Unit	Test Conditions	Note
V_{DSmax}	Drain-Source Voltage	1200	V	$V_{GS}=0V, I_D=100\mu A$	
V_{GSmax}	Gate-Source Voltage	-8/+22	V	Absolute maximum values	
V_{GSop}	Gate-Source Voltage	-4/+18	V	Recommended operational values	
I_D	Continuous Drain Current	120	A	$V_{GS}=18V, T_c=25^{\circ}C$	Fig. 19
		85		$V_{GS}=18V, T_c=100^{\circ}C$	
$I_{D(pulse)}$	Pulsed Drain Current	250	A	Pulse width t_p limited by T_{Jmax}	Fig. 22
P_D	Power Dissipation	375	W	$T_c=25^{\circ}C, T_J=175^{\circ}C$	Fig. 20
T_J, T_{STG}	Operating Junction and Storage Temperature	-55 to +175	$^{\circ}C$		
T_L	Solder Temperature, 1.6mm from case for 10s	260	$^{\circ}C$		
M_d	Mounting Torque, (M3 or 6-32 screw)	1	Nm		
		8.8	lbf-in		

Electrical Characteristics (T_C=25°C unless otherwise specified)

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions	Note
V _{(BR)DSS}	Drain-Source Breakdown Voltage	1200	/	/	V	V _{GS} =0V, I _D =100μA	
V _{GS(th)}	Gate Threshold Voltage	1.9	2.6	4.0	V	V _{DS} =V _{GS} , I _D =23mA	Fig. 11
		/	1.8	/		V _{DS} =V _{GS} , I _D =23mA, T _J =175°C	
I _{DSS}	Zero Gate Voltage Drain Current	/	1	100	μA	V _{DS} =1200V, V _{GS} =0V	
I _{GSS+}	Gate-Source Leakage Current	/	10	250	nA	V _{DS} =0V, V _{GS} =22V	
I _{GSS-}	Gate-Source Leakage Current	/	10	250	nA	V _{DS} =0V, V _{GS} =-8V	
R _{DS(on)}	Drain-Source On-State Resistance	/	16	22.3	mΩ	V _{GS} =18V, I _D =75A	Fig. 4,5,6
		/	28	/		V _{GS} =18V, I _D =75A, T _J =175°C	
g _{fs}	Transconductance	/	41.4	/	S	V _{DS} =20V, I _{DS} =75A	Fig. 7
		/	36.5	/		V _{DS} =20V, I _{DS} =75A, T _J =175°C	
C _{iss}	Input Capacitance	/	4817	/	pF	V _{GS} =0V	Fig. 17,18
C _{oss}	Output Capacitance	/	207	/		V _{DS} =1000V	
C _{rss}	Reverse Transfer Capacitance	/	45	/		f=1MHz	
E _{oss}	C _{oss} Stored Energy	/	104	/	μJ	V _{AC} =25mV	Fig. 16
E _{ON}	Turn-On Switching Energy	/	2.1	/	mJ	V _{DS} =800V, V _{GS} =-4V/18V	
E _{OFF}	Turn-Off Switching Energy	/	1.6	/		I _D =30A, R _{G(ext)} =2.5Ω, L=100μH	
t _{d(on)}	Turn-On Delay Time	/	150	/	ns	V _{DS} =800V, V _{GS} =-4V/18V, I _D =30A R _{G(ext)} =2.5Ω, R _L =20Ω	
t _r	Rise Time	/	38	/			
t _{d(off)}	Turn-Off Delay Time	/	108	/			
t _f	Fall Time	/	35	/			
R _{G(int)}	Internal Gate Resistance	/	4.5	/	Ω	f=1MHz, V _{AC} =25mV	
Q _{GS}	Gate to Source Charge	/	66	/	nC	V _{DS} =800V	Fig. 12
Q _{GD}	Gate to Drain Charge	/	48	/		V _{GS} =-4V/18V	
Q _G	Total Gate Charge	/	269	/		I _D =30A	

Reverse Diode Characteristics

Symbol	Parameter	Typ.	Max.	Unit	Test Conditions	Note
V _{SD}	Diode Forward Voltage	4.2	/	V	V _{GS} =-4V, I _{SD} =37.5A, T _J =25°C	Fig. 8,9,10
		3.9	/		V _{GS} =-4V, I _{SD} =37.5A, T _J =175°C	
I _S	Continuous Diode Forward Current	/	120	A	T _C =25°C	
t _{rr}	Reverse Recover Time	54	/	ns	V _R =800V, I _{SD} =30A	
Q _{rr}	Reverse Recovery Charge	630	/	nC		
I _{rrm}	Peak Reverse Recovery Current	19	/	A		

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit	Test Conditions	Note
R _{θJC}	Thermal Resistance from Junction to Case	0.23	/	°C/W		Fig. 21
R _{θJA}	Thermal Resistance from Junction to Ambient	/	40			

RATING AND CHARACTERISTICS CURVES (RSM120N120T7L)

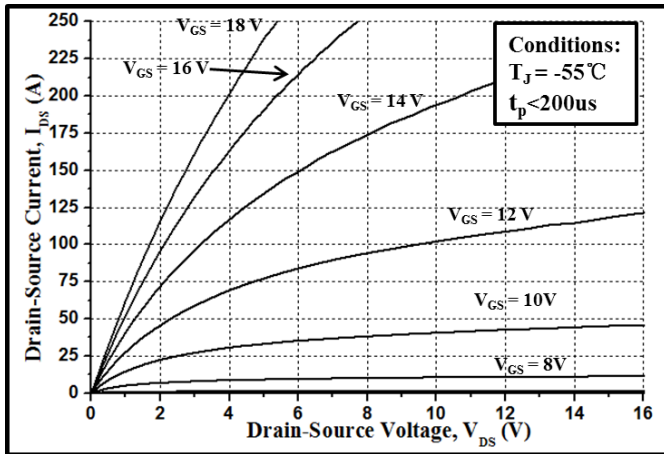


Figure 1. Output Characteristics $T_J = -55^\circ\text{C}$

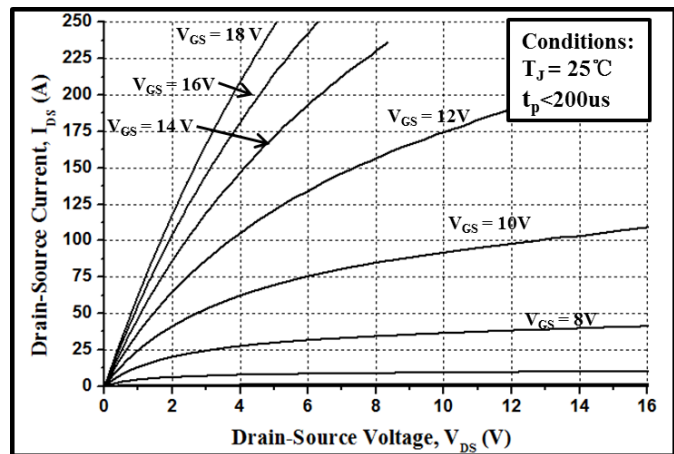


Figure 2. Output Characteristics $T_J = 25^\circ\text{C}$

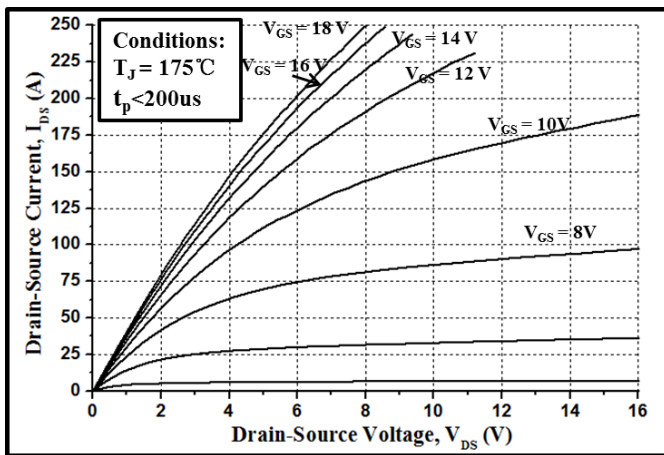


Figure 3. Output Characteristics $T_J = 175^\circ\text{C}$

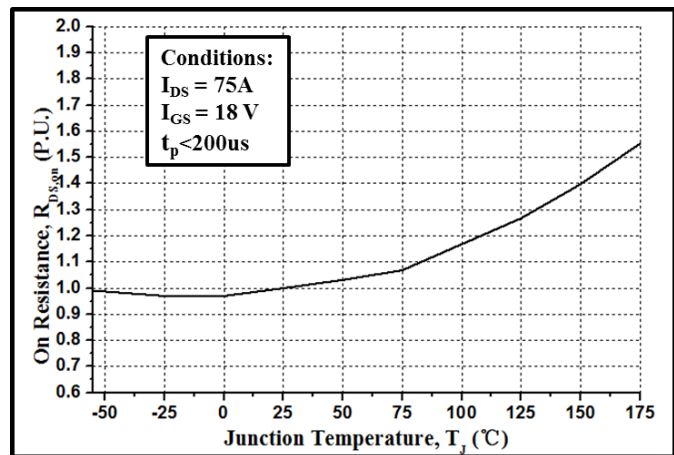


Figure 4. Normalized On-Resistance vs. Temperature

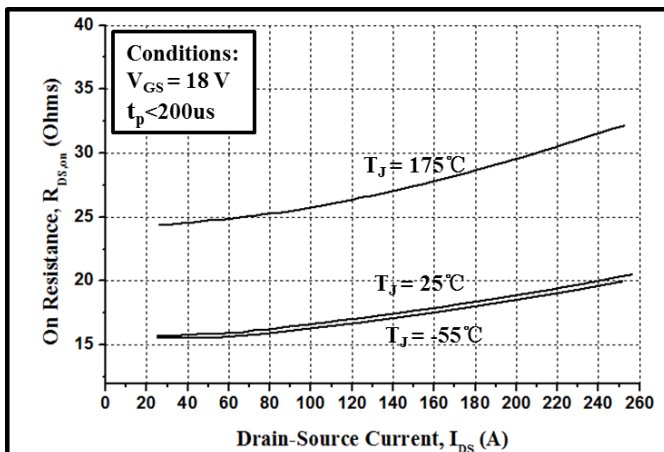


Figure 5. On-Resistance vs. Drain Current
For Various Temperatures

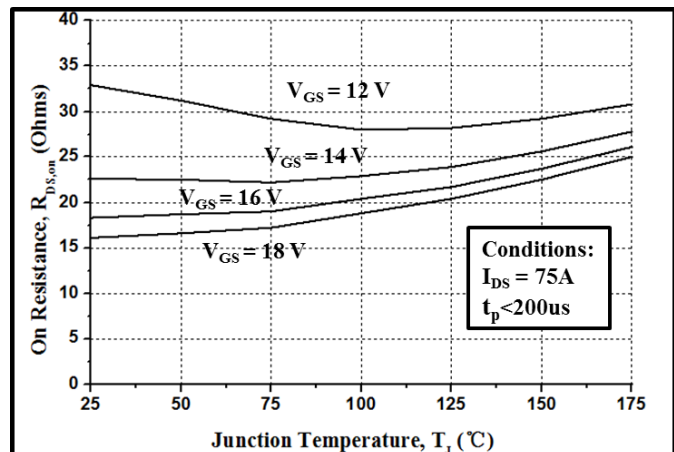


Figure 6. On-Resistance vs. Temperature
For Various Gate Voltage

RATING AND CHARACTERISTICS CURVES (RSM120N120T7L)

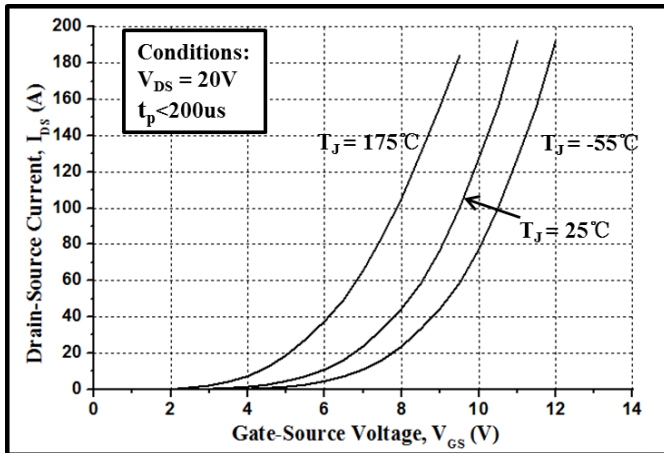


Figure 7. Transfer Characteristic for Various Junction Temperatures

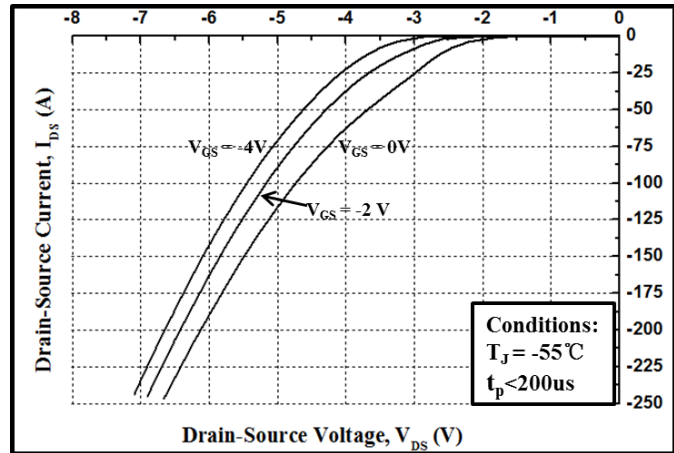


Figure 8. Body Diode Characteristic at -55°C

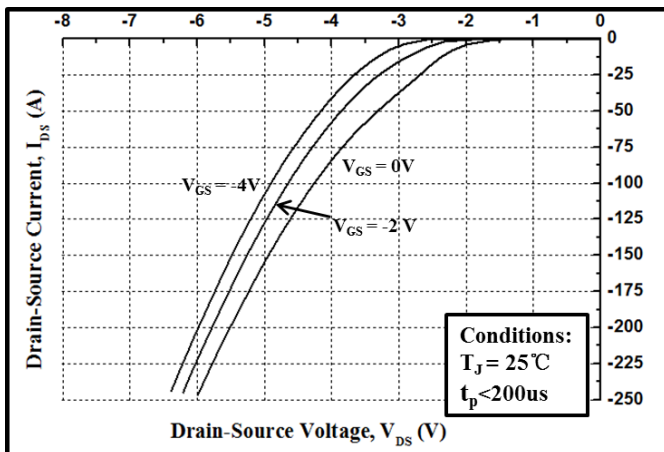


Figure 9. Body Diode Characteristic at 25°C

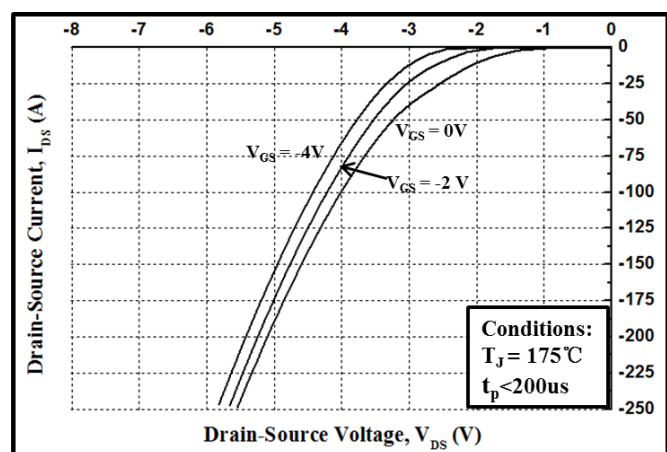


Figure 10. Body Diode Characteristic at 175°C

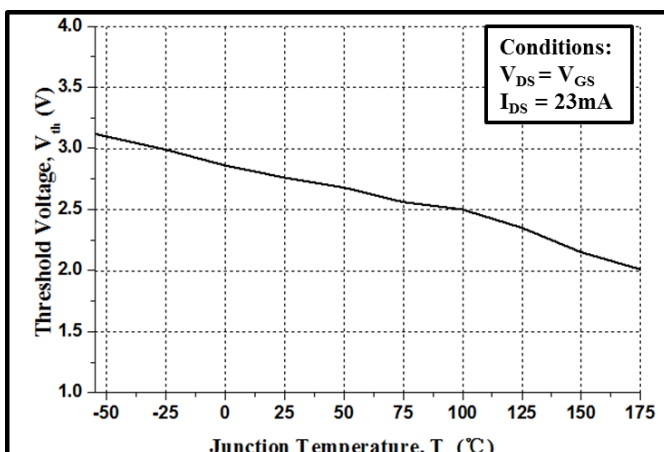


Figure 11. Threshold Voltage vs. Temperature

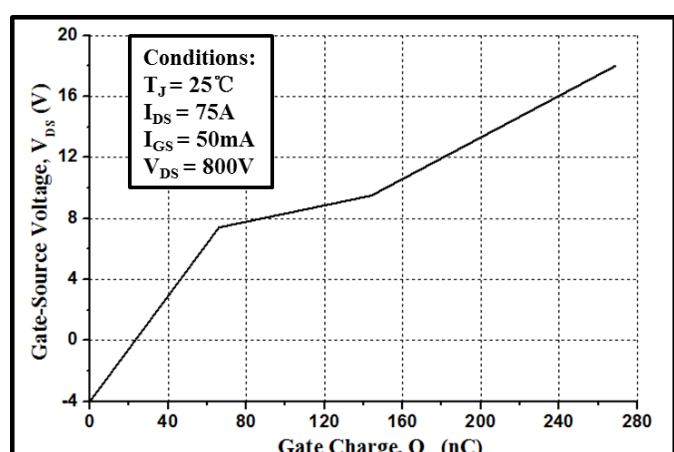


Figure 12. Gate Charge Characteristics

RATING AND CHARACTERISTICS CURVES (RSM120N120T7L)

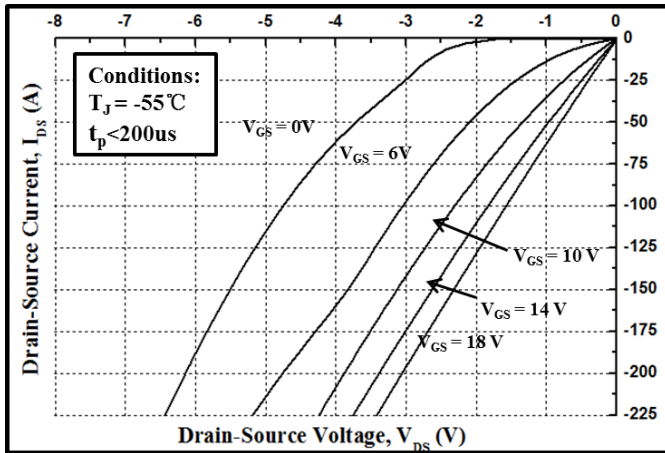


Figure 13. 3rd Quadrant Characteristic at -55°C

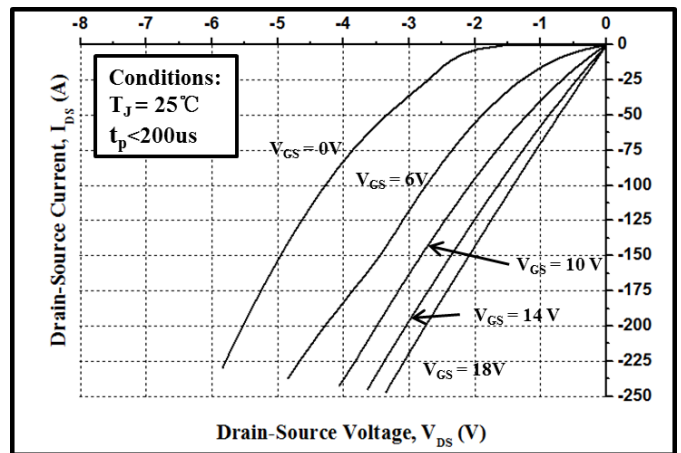


Figure 14. 3rd Quadrant Characteristic at 25°C

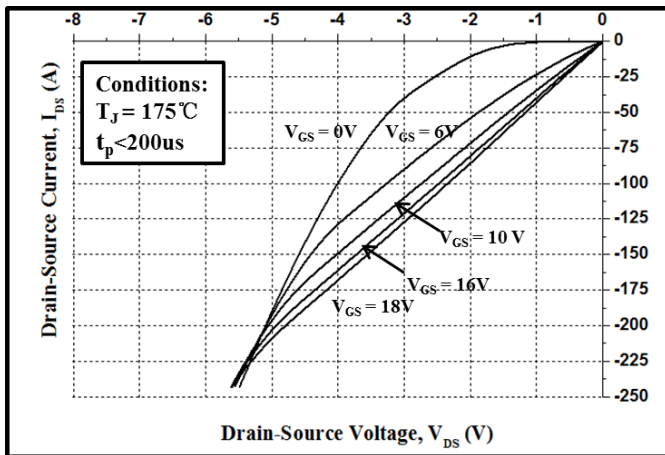


Figure 15. 3rd Quadrant Characteristic at 175°C

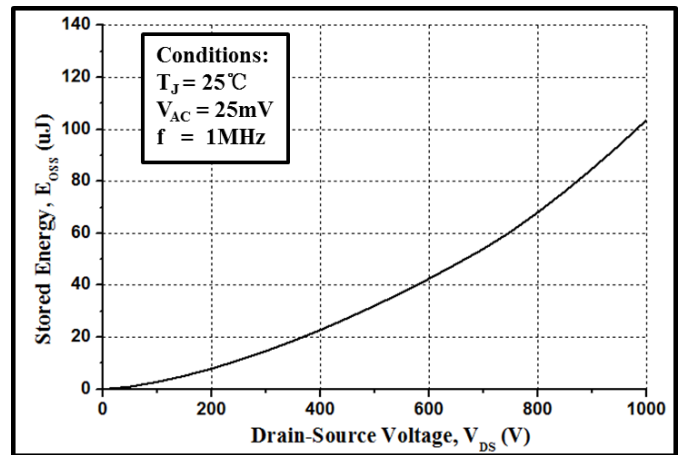


Figure 16. Output Capacitor Stored Energy

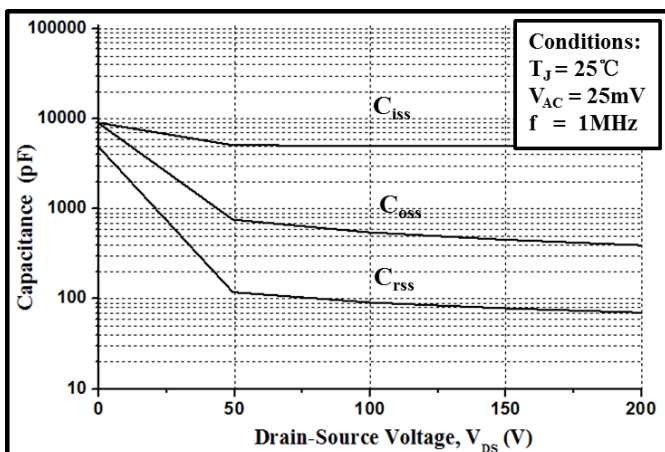


Figure 17. Capacitances vs. Drain-Source Voltage (0 - 200V)

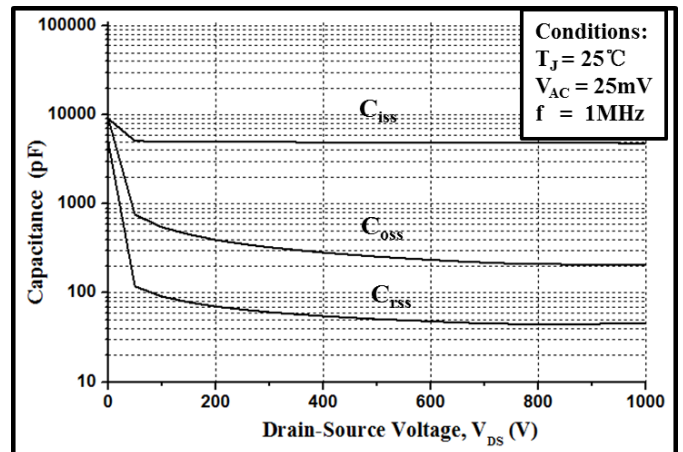


Figure 18. Capacitances vs. Drain-Source Voltage (0 - 1000V)

RATING AND CHARACTERISTICS CURVES (RSM120N120T7L)

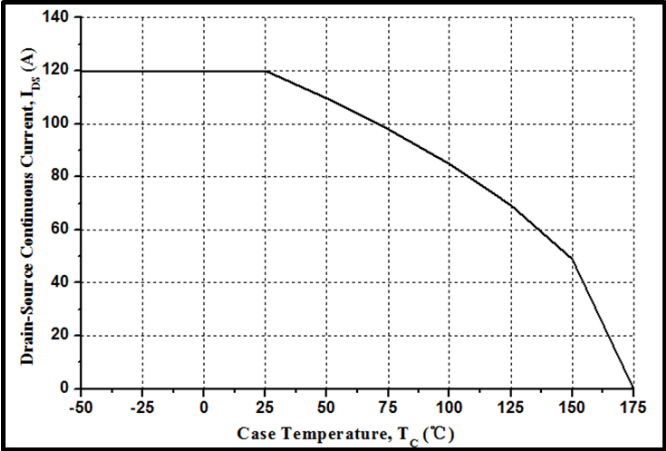


Figure 19. Continuous Drain Current vs. Case Temperature

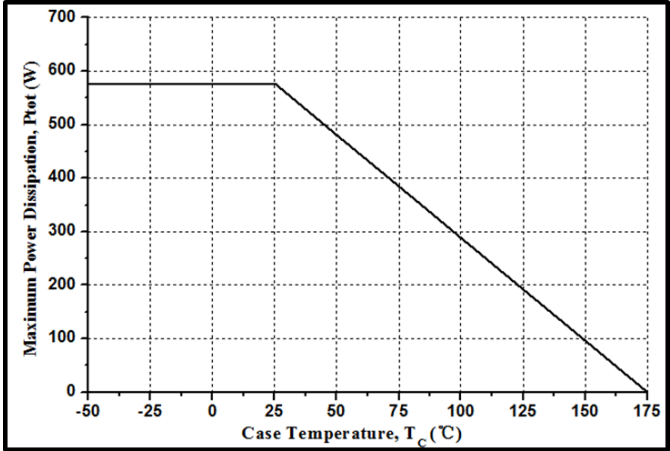


Figure 20. Maximum Power Dissipation vs. Case Temperature

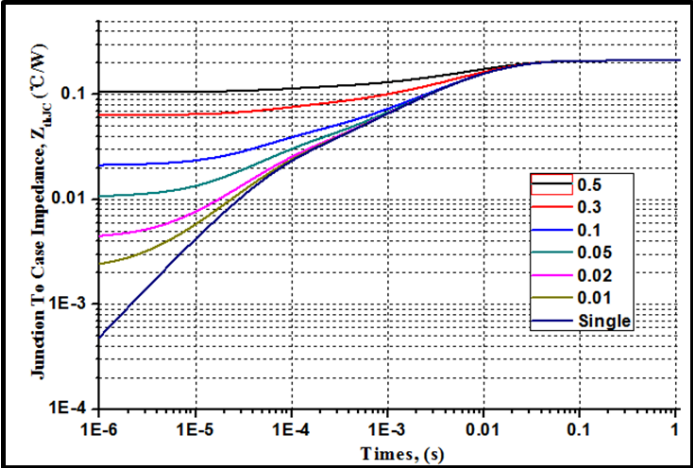


Figure 21. Transient Thermal Impedance (Junction - Case)

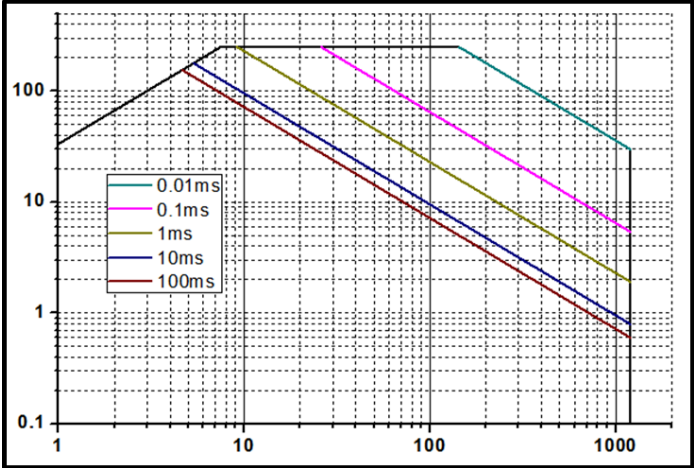


Figure22. Safe Operating Area

Test Circuit Schematic

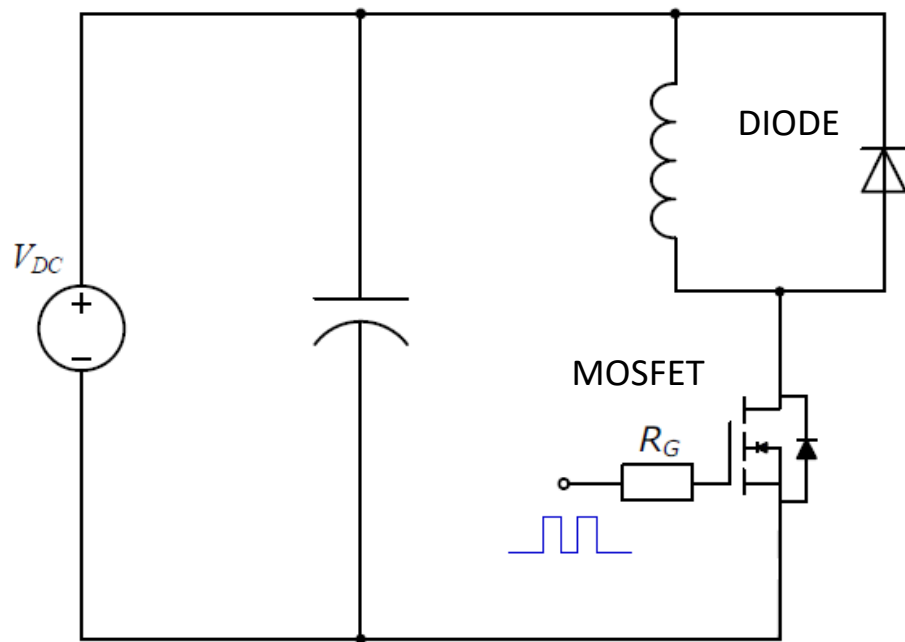
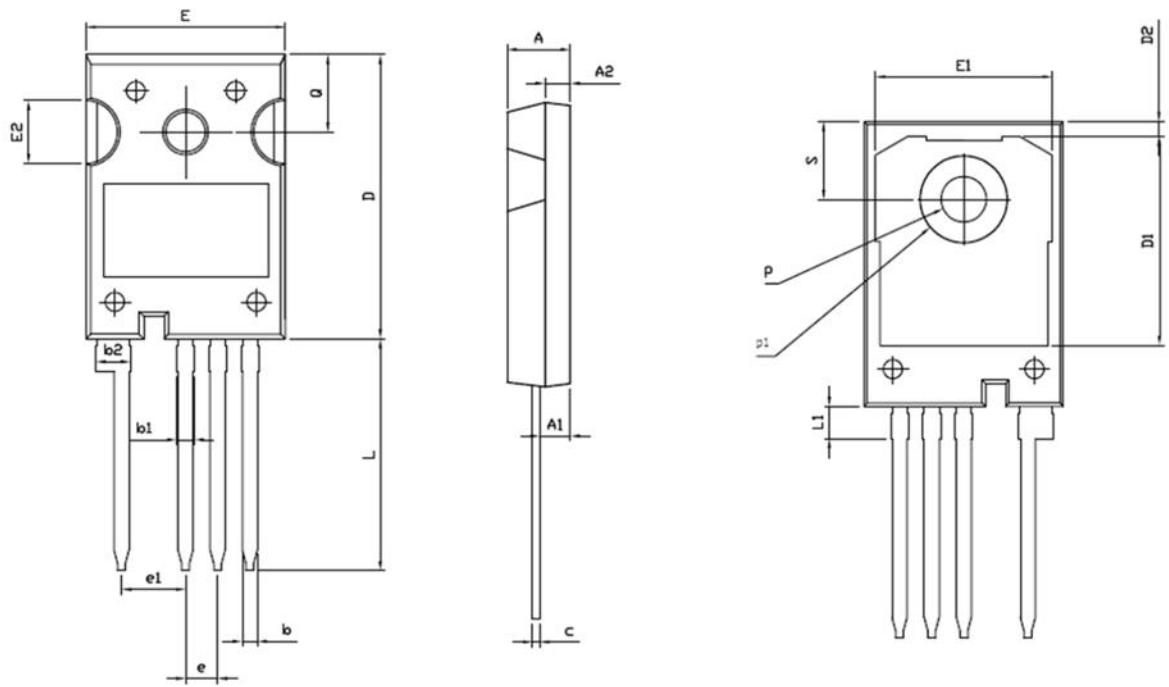
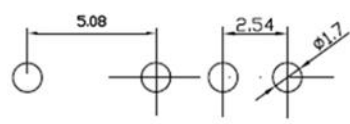


Figure 23. Clamped Inductive Switching
Waveform Test Circuit

Package Dimensions



RECOMMENDED LAND PATTERN



UNIT: mm

	MIN	NOM	MAX
A2	1.85	2.00	2.15
b	1.05	1.20	1.35
b1	1.00	1.30	1.60
b2	2.35	2.65	2.95
c	0.50	0.60	0.70
D	22.34	22.54	22.74
D1	16.00	16.50	17.00
D2	0.97	1.17	1.37
e	2.34	2.54	2.74
e1	4.88	5.08	5.28
E	15.60	15.80	16.00
E1	13.50	14.00	14.50
E2	4.80	5.00	5.20
L	18.08	18.38	18.68
L1	2.38	2.58	2.78
p	3.50	3.60	3.70
p1	6.60	6.80	7.00
Q	6.00	6.15	6.30
S	6.00	6.15	6.30

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